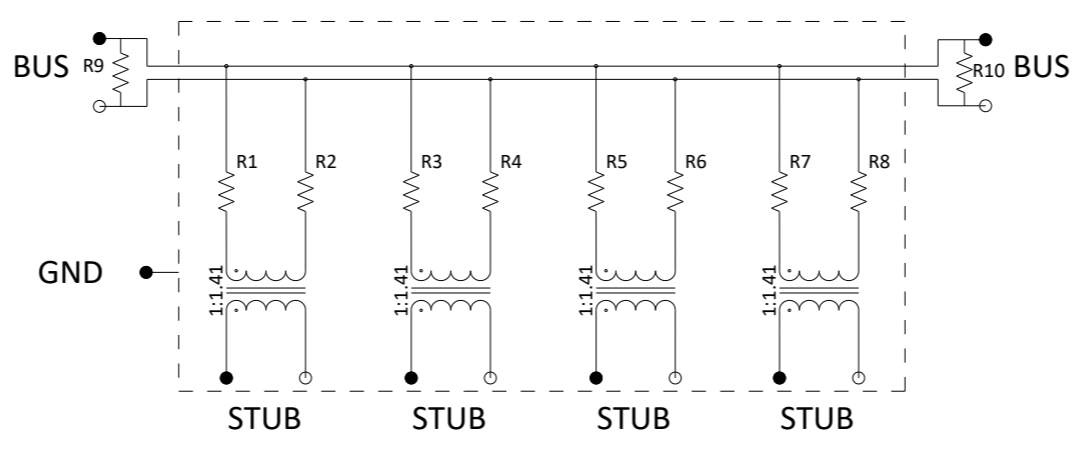


SCHMATIC DIAGRAM



- 1.0 ELECTRICAL SPECIFICATIONS: IAW MIL-STD-1553B**
- 1.1 COMMON MODE REJECTION: -45.0 Db MAX @ 1.0MHz
  - 1.2 DROOP: 20% MAX (250kHz)
  - 1.3 OVERSHOOT & RINGING: ± 1.0V PEAK (250kHz SQUARE WAVE WITH 100Ns)
  - 1.4 STUB VOLTAGE: 1.0V TO 14.0V P-P; LINE TO LINE; SIGNAL VOLTAGE, TRANSFORMER COUPLING
  - 1.5 INPUT IMPEDANCE OF BUS: 3000 OHMS MIN. (75kHz - 1.0MHz), STUB WITH OPEN CIRCUIT
  - 1.6 CHARACTERISTIC IMPEDANCE:  $Z_0=78$  OHMS
  - 1.7 FAULT PROTECTION: 59 OHMS ± 1% 1W (R1-R8) IN SERIES WITH TRANSFORMER WINDING ON BUS SIDE
  - 1.8 TERMINATION RESISTOR VALUE: 78.7 OHMS ± 1% 2W (R9, R10) BUS TERMINATION
- 2.0 MECHANICAL SPECIFICATIONS:**
- 2.1 ENCLOSURE MATERIAL: TINPLATE 0.5mm THK.
- 3.0 ENVIRONMENTAL:**
- 3.1 OPERATING TEMPERATURE RANGE: -55°C TO 125°C
  - 3.2 VIBRATION: MIL-STD-810G\_CHG-1 METHOD 514.7 PROCEDURE I
  - 3.3 SHOCK: MIL-STD-810G\_CHG-1 METHOD 516.7 PROCEDURE V
  - 3.4 HIGH TEMPERATURE OPERATING: MIL-STD-810G\_CHG-1 METHOD 501.6 PROCEDURE II, +125°C
  - 3.5 LOW TEMPERATURE OPERATING: MIL-STD-810G\_CHG-1 METHOD 502.6 PROCEDURE II, -55°C
  - 3.6 HIGH TEMPERATURE STORAGE: MIL-STD-810G\_CHG-1 METHOD 501.6 PROCEDURE I, +125°C
  - 3.7 LOW TEMPERATURE STORAGE: MIL-STD-810G\_CHG-1 METHOD 502.6 PROCEDURE I, -55°C
  - 3.8 RAIN: MIL-STD-810G METHOD 506.5 PROCEDURE I

**! PLACING COMPONENTS UNDER THE PCB MOUNT COUPLER IS NOT RECOMMENDED.**

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS.

PRODUCT NAME					
PCB TYPE BUS COUPLER 4 DTRM					
DOCUMENT NAME					www.delco.com.tr
DE8134 - TECHNICAL DRAWING					
SIZE	SCALE	REVISION	REVISION DATE	SHEET	
A3	2:1	1	28.11.2023	1/1	

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